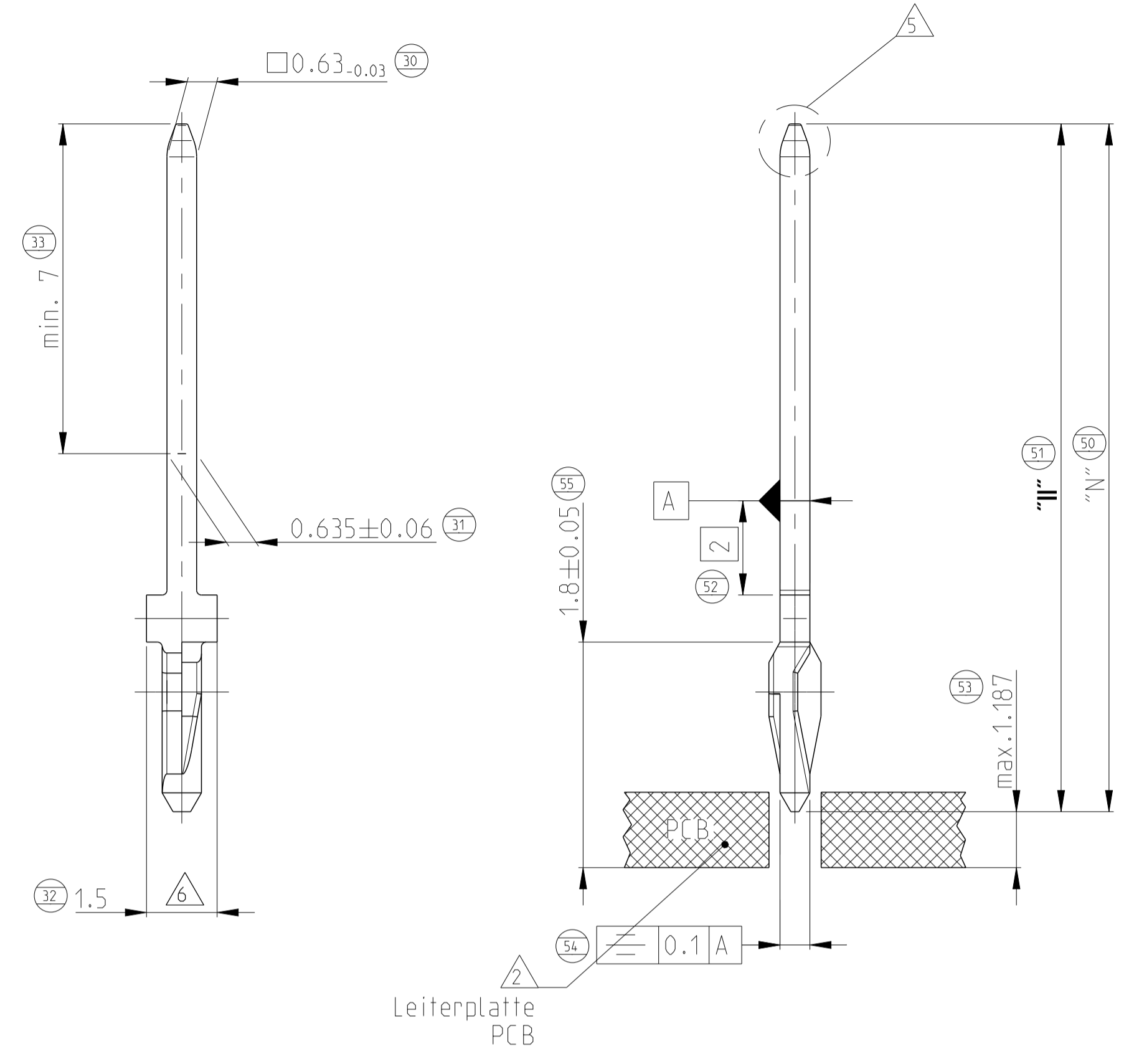
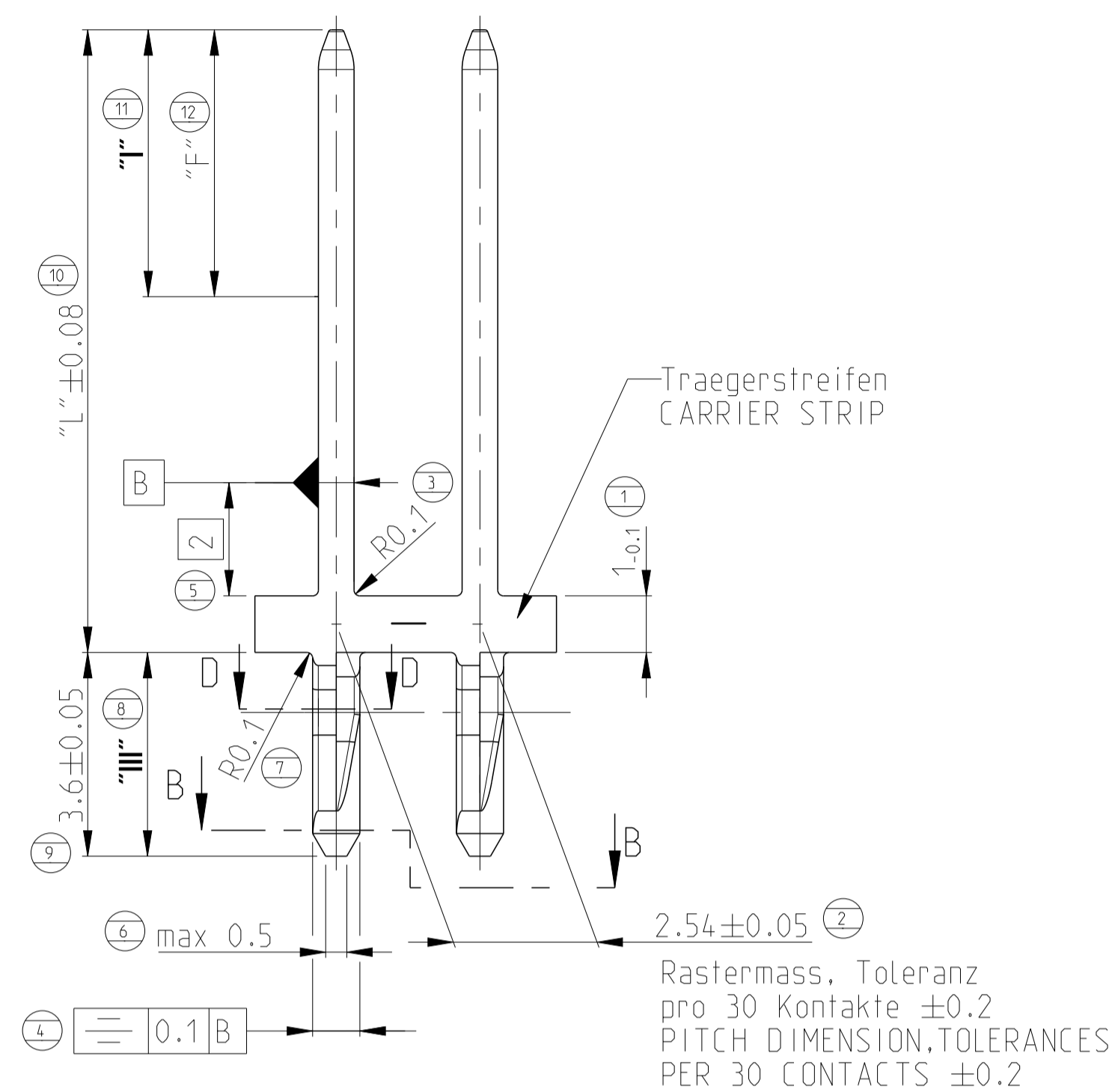


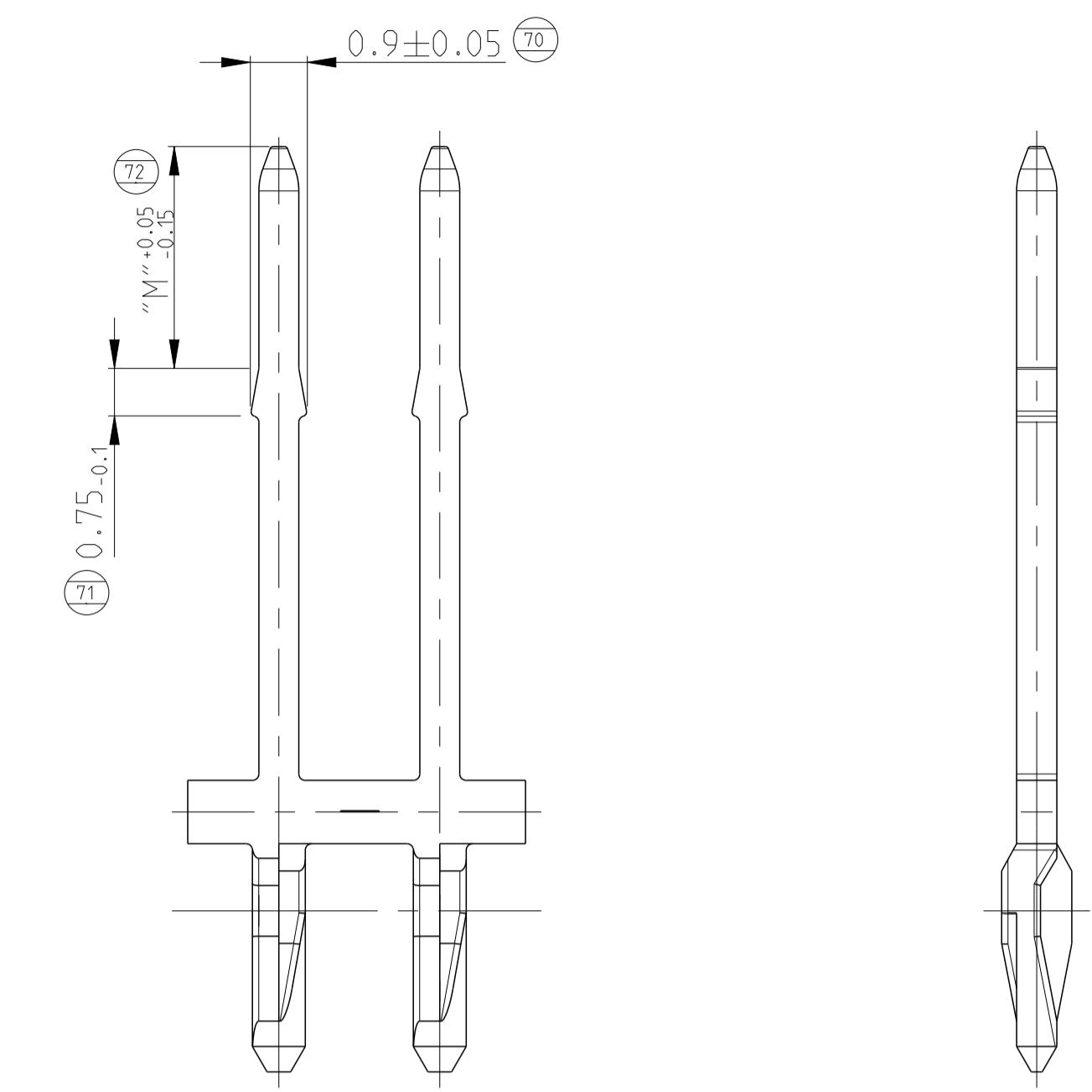
| LOC | DIST | REVISIONS | | | |
|--------------|------|-----------------------------------|-----------|------|------|
| A1 | | NO. | DATE | BY | CHK |
| PROJEKT NR.: | A20 | NEW PN 7-963964-9 ADDED | 05NOV2015 | HO. | ZITZ |
| | A21 | TOLERANCE MODIFIED | 01DEC2015 | MAH. | LACK |
| | A22 | NEW DASH VARIANT 8-963964-7 ADDED | 23JUN2016 | dwm | JK |
| | A23 | NEW DASH VARIANT 8-963964-8 ADDED | 19JAN2017 | ML | PS |

VERSION A

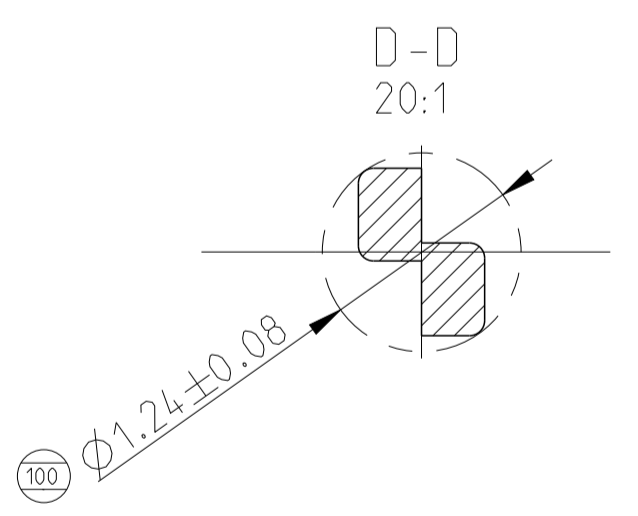
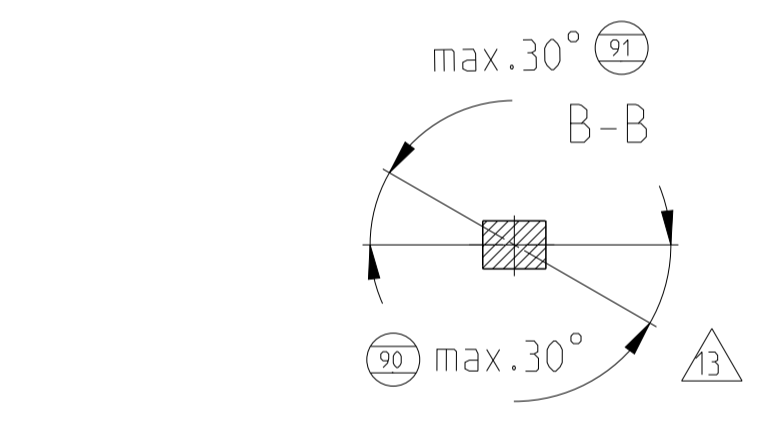
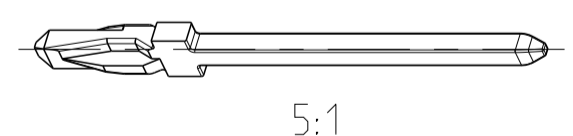


VERSION B

FOR MISSING DIMENSIONS SEE VERSION A



- 1 Massgebend ist der deutsche Text
 ONLY THE GERMAN LANGUAGE VERSION SHALL BE BINDING
- 2 Verwendung fuer Leiterplattendicke: 1.6 ± 0.14mm
 USED ON PCB THICKNESS: 1.6 ± 0.14mm
- 3
- 4 Lötbarkeit nach DIN 40046
 SOLDERABILITY ACCORDING TO DIN 40046
- 5 Kontaktstift siehe Zeichnung, TE 114-94201 Version B
 CONTACT PIN SEE DRAWING TE 114-94201 VERSION B
- 6 Zustand vor dem Einpressen
 STATUS BEFORE INSERTION
- 7 Zulaessige Saebelfoermigkeit: 40mm/m
 PERMITTED "SABERSHARPNESS": 40mm/m
- 8 Einpresszone fuer 1.6mm Leiterplatte
 Anforderung an Leiterplattenloch, siehe Tabelle 1
 PRESS-IN AREA FOR 1.6mm PCB
 REQUIREMENTS ON PCB HOLE. SEE TABLE 1
- 9 Verpackungseinheit: 50.000 Stck. auf Einweg Kunststoff-Spule Ø 588mm
 mit Zwischenlagenpapier, 3 Spulen im Karton
 PACKAGING UNIT: 50.000 PCS ON ONE-WAY PLASTIC REEL DIA.588MM
 WITH INTERLEAVING PAPER, 3 REELS IN BOX.
- 10 Lochaufbau (Zinn/Blei) in der Leiterplatte (siehe Tabelle 1)
 HOLE CONSTRUCT (TIN/LEAD) FOR PCB (SEE TABLE 1)
- 11 Lochaufbau (Nickel/Gold) in der Leiterplatte (siehe Tabelle 1)
 HOLE CONSTRUCT (NICKEL/GOLD) FOR PCB (SEE TABLE 1)
- 12 Lochaufbau (Zinn) in der Leiterplatte (siehe Tabelle 1)
 HOLE CONSTRUCT (TIN) FOR PCB (SEE TABLE 1)
- 13 Verdrehung Action Pin Spitze max. 30°
 DISTORTION OF ACTION PIN TIP MAX. 30 DEG.
- 14 Material spezifiziert nach UNS C19002
 MATERIAL SPECIFIED ACCORDING TO UNS C19002
- 15 Spulen mit Kunststoff-Spule PN 1-1498100-8 mit
 Zwischenlagenpapier PN 1-740973-2, Transportkarton 973051-2
 REELED ONTO PLASTIC REEL PN 1-1498100-8 WITH INTERLEAVING
 PAPER PN 1-740973-2, SHIPPING CARTON 973051-2
- 16 REELED ONTO REEL PN 725654-9 WITH
 INTERLEAVING PAPER PN 740973-3, SHIPPING
 CARTON 973051-2
 Spulen mit Spule PN 725654-9 mit
 Zwischenlagenpapier PN 704973-3, Transportkarton 973051-2
- 17 1.3 µm bis 2.5 µm NICKEL UPON PLATING AFTER FORMING SEQUENCE
 1.3 µm bis 2.5 µm Nickel nach Formgebung ueber alles



Lochaufbau in der Leiterplatte HOLE CONSTRUCT FOR PCB

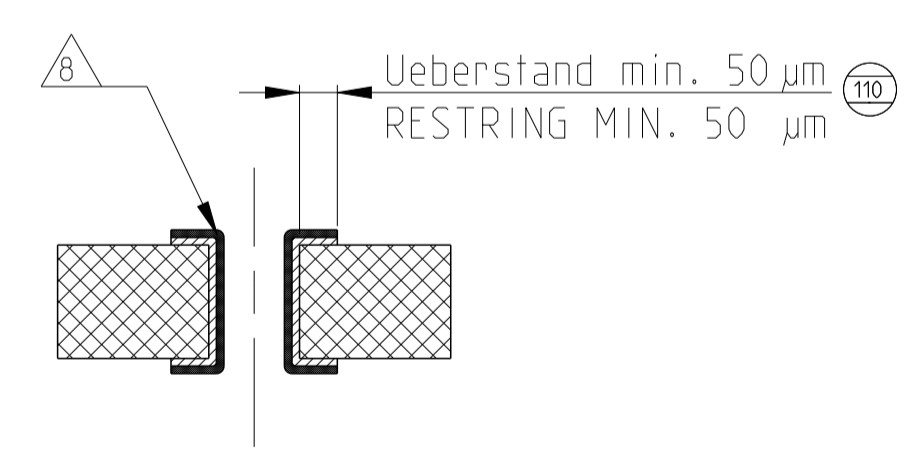


Tabelle 1
 TABLE 1

| Durchplattierte Bohrung, Spezifikation PLATING ACROSS OF HOLE, SPEC. | | | |
|---|------------------|------------------|-----------------------|
| Lochaufbau LP HOLE CONSTRUCT PCB | 10 | 11 | 12 |
| Kupferschicht COPPER COATING | 25-75 µm | 25-75 µm | 25-50 µm |
| Zinn/Blei Schicht TIN/LEAD COATING | 4-10 µm | - | - |
| Zinn Schicht TIN COATING | - | - | 0.5-1.5 µm |
| Nickel Schicht NICKEL COATING | - | max. 5 µm | - |
| Gold Schicht GOLD COATING | - | max. 0.2 µm | - |
| Bohr Ø HOLE DIA. | 1.15 ± 0.025 | 1.15 ± 0.025 | 1.15 ± 0.025 |
| Plattierter Ø PLATED DIA. | 1 +0.09 -0.06 | 1 +0.09 -0.06 | 1.07 +0.055 -0.045 |

Tabelle 2
 TABLE 2

| Oberflaeche/SURFACE | |
|---------------------|---|
| Zone "I" AREA | Goldaufuehrung: 0.8 µm bis 2 µm Au ueber Ni GOLD VERSION: 0.8 µm TO 2 µm Au OVER Ni Zinn-Ausuehrung: 1 µm bis 3 µm Sn TIN-VERSION: 1 µm TO 3 µm Sn SILVER-VERSION 1.5 µm to 5 µm Ag over Ni |
| Zone "II" AREA | Schichtdicke: 1.3 µm bis 2.2 µm Ni COAT THICKNESS: 1.3 µm TO 2.2 µm Ni FOR PN 8-963964-8 regarding note 17 |
| Zone "III" AREA | Schichtdicke: 0.8 µm bis 1.8 µm Sn ueber Ni COAT THICKNESS: 0.8 µm TO 1.8 µm Sn OVER Ni |

Tabelle 3
 TABLE 3

| VERSION | TE CONNECTIVITY BESTELL-NR. ORDER NO. | REV. | MATERIAL | OBERFLAECHE SURFACE AREA "F" | PCB-HOLE SPEC. LP-Bohrung Spez. | GRAMM GEWICHT WEIGHT | "F" | "L" | "M" | "N" |
|------------|---|-----------|--------------|------------------------------------|--|----------------------------|-------|------|------|-----|
| A | 7-963964-9 | A | CuNiSi R580S | Zinn/TIN | 0.05 | 7 | 21.3 | - | 24.9 | |
| | 6-963964-5 | A | | Zinn/TIN | | 7 | 11.4 | - | 15 | |
| | 8-963964-7 | A | | Zinn/TIN | | 7 | 11.1 | - | 14.7 | |
| | 2-963964-8 | A | | Zinn/TIN | | 7 | 9.2 | - | 12.8 | |
| | 8-963964-8 | A | | Silver/Silber | | 7 | 11.1 | - | 14.7 | |
| 3-963964-7 | A | Gold/GOLD | | 5.5 | | 11.1 | - | 14.7 | | |
| 2-963964-7 | A | Zinn/TIN | | 7 | | 11.1 | - | 14.7 | | |
| 2-963964-6 | B | Zinn/TIN | | 7 | | 13.6 | 7.75 | 17.2 | | |
| 2-963964-5 | C | Zinn/TIN | | 8.2 | | 17.8 | 9.25 | 21.4 | | |
| 9-963964-4 | A | Zinn/TIN | | 7 | | 13.6 | 7.75 | 17.2 | | |
| A | 8-963964-4 | B | Zinn/TIN | 7 | 9.8 | - | 13.4 | | | |
| | 3-963964-4 | A | Gold/GOLD | 5.5 | 9.8 | - | 13.4 | | | |
| | 2-963964-4 | B | Zinn/TIN | 7 | 9.8 | - | 13.4 | | | |
| | 1-963964-4 | B | Gold/GOLD | 5.5 | 9.8 | - | 13.4 | | | |
| | 2-963964-3 | B | Zinn/TIN | 7 | 8.05 | - | 11.65 | | | |
| 1-963964-3 | B | Gold/GOLD | 5.5 | 8.05 | - | 11.65 | | | | |

A23 THE PN 8-963964-8 is in development status
 The 8-963964-8 is not released for serial production
 PN 8-963964-8 ist in dem Entwicklungsstand.
 Part number 8-963964-8 ist nicht freigegeben fuer serienproduktion

| | | | |
|--|--|---|--|
| THIS DRAWING IS A CONTROLLED DOCUMENT. DIMENSIONING AND TOLERANCING PER GPS (ISO STANDARDS) | | OWN C. Beu 02DEC2002 | TE Connectivity |
| TOLERANCES UNLESS OTHERWISE SPECIFIED: ALLE MASSTOLERANZEN | | CHK T. Sieler 10DEC2002 | |
| DIMENSIONS: MASSENMESSUNG (MM) | 0 PLC ±0.5 1 PLC ±0.2 2 PLC ±0.1 3 PLC ±0.1 4 PLC ±0.1 | APVD | NAME |
| MATERIAL CUNISI R580S | FINISHOBERFLAECHE/FARB | PRODUCT SPEC PRODUCT SPEC 108-18643 | MQS ACTION PIN fuer 1mm Loch, freistehend |
| CUSTOMER DRAWING | | SIZE A1 | RESTRICTED TO NUR FUEHR |
| /KUNDENZEICHNUNG | | DRAWING NO. 963964 | SHEET 1 |
| SCALE 10:1 | | OF 1 | REV A23 |